

Fig. 1 Schematic illustration of the procedure for fabrication of micro-sized tensile specimens

(3-5)

1 μm TiN

TiN Si

MEMS

2.5kW (frequency 25 kHz and duty cycle 50%)

5cm

2.2

3×10⁻⁵ Torr

Ar 가

2.4×10⁻³ Torr

2.8×10⁻³ Torr

N₂ 가

Ti (target)

(targetpower) DC

(Si wafer)

2.1 TiN

TiN film 500μm Si(100)

(CFUBMS; closed-field unbalanced magnetron sputtering)

Si TiN

(Si₃N₄) 1μm

LPCVD(Low pressure chemical vapor deposition) 140mTorr

40Å/min Si

Si (size : diameter 250 mm, L=300 mm)

MEMS

Fig. 1

1μm

(photolithography)

(CFUBMS) TiN

TiN

()

TiN TiN

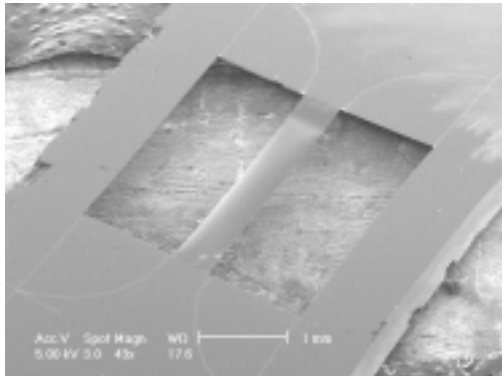


Fig.2 Specimen fabricated by MEMS process

PECVD(Plasma Enhanced Chemical Vapor Deposition) TMAH HF
 49%

Fig. 1 (h)

Fig. 2 가 50μm, 100μm

500μm

2.3

Fig. 3

(ESPI)

500 mN 가

ESPI

2

(frame grabber)

CCD

Fig, 3

4.5 nm

Fig. 3 Schematic drawing of micro-tensile testing system used in this stud

$$\epsilon = \frac{\lambda}{2D_p \cos \theta} \quad (1)$$

(He-Ne

632.8nm)

Dp

3.

3.1

(sputtering::CFUBMS) Si

TiN

(nano indentation test)

(nano-indenter XP:MTS)

Berkovich

300 nm

300 nm

1μm

TiN

Fig. 4

(continuous stiffness method;CSM)

45Hz

가

0.05s⁻¹

10

90%

10 μ N/s

Fig. 4

50 nm

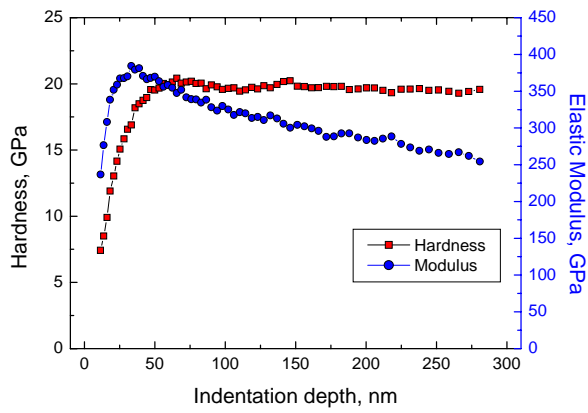


Fig. 4 Variation of hardness and elastic modulus with indentation depth in TiN film.

3.2

Fig. 5

Fig. 5

가

가

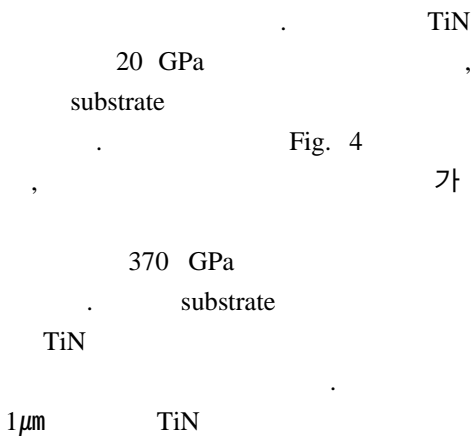


Fig. 4

가

가

Fig. 7

1 μm

TiN

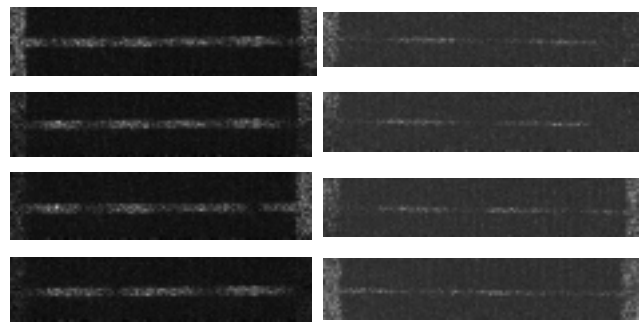
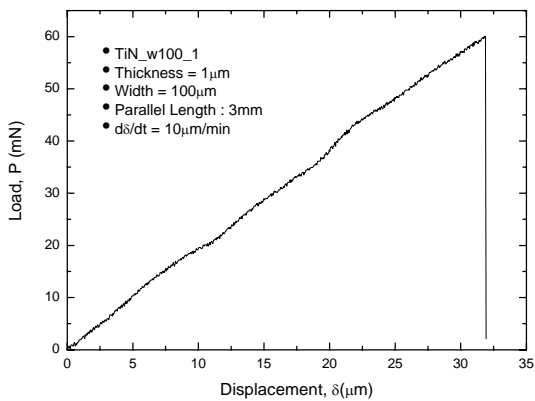
Fig. 7

50 μm

100 μm

Fig. 6

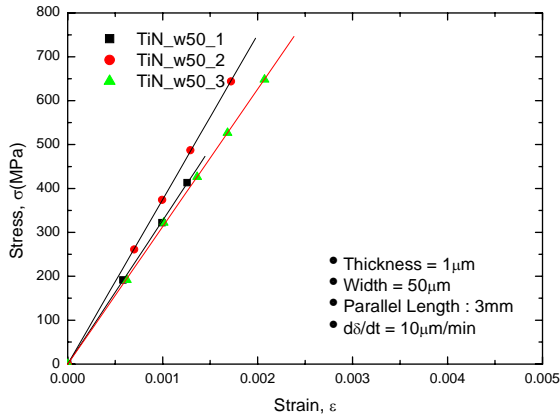
TiN



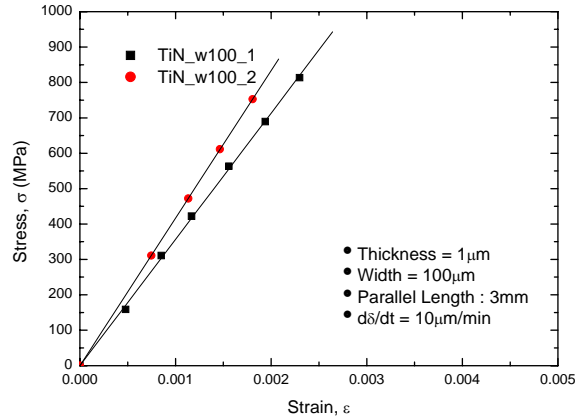
For the specimen 100 μm wide

For the specimen 50 μm wide

Fig. 5 Typical tensile load-displacement curve and the speckle patterns for narrow and medium specimen with progress of the tensile deformation.



(a) for narrow (50 μm wide) specimen



(b) for medium (100 μm wide) specimen

Fig. 6 Tensile stress-strain curve in TiN thin film

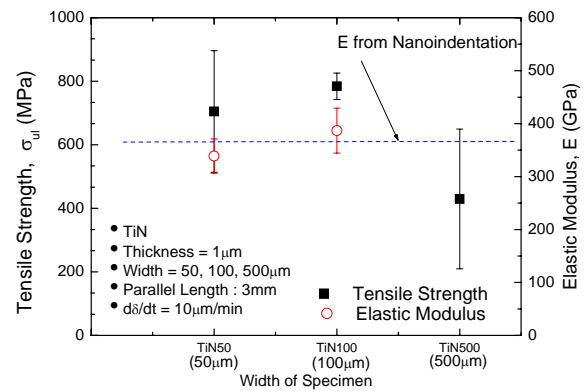
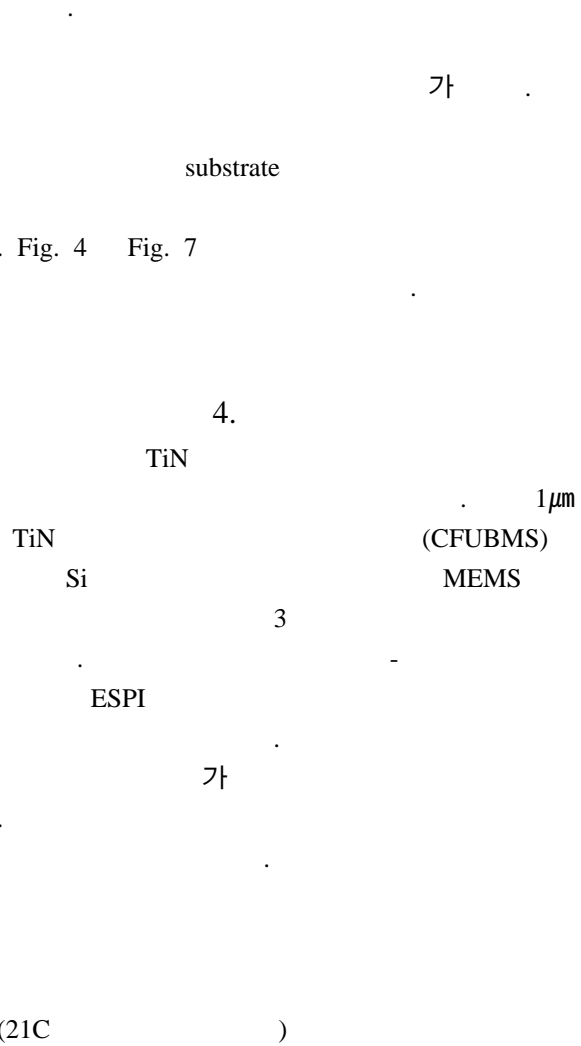


Fig. 7 Tensile strength and elastic material for TiN thin film

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